



COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	BV _{DSS}	R _{DS(ON)} max	I _D Max T _A = +25°C
02	30V	$21m\Omega$ @ $V_{GS} = 10V$	8.5A
Q2		$32m\Omega$ @ $V_{GS} = 4.5V$	7.2A
Q1	-30V	$39m\Omega$ @ $V_{GS} = -10V$	-7A
		53mΩ @ V _{GS} = -4.5V	-5.6A

Description and

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Power Management Functions
- Analog Switch
- Load Switch

Features

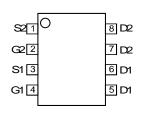
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>DMC3021LSDQ</u>)

Mechanical Data

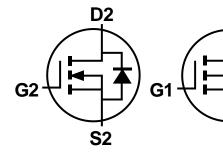
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Lead
 Frame. Solderable per MIL-STD-202, Method 208⁽³⁾
- Weight: 0.072 grams (Approximate)







Top View



N-Channel MOSFET

P-Channel MOSFET

D1

Ordering Information (Note 4)

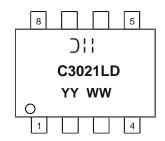
Ī	Part Number	Case	Packaging	
١	DMC3021LSD-13	SO-8	2500/Tape & Reel	

SO-8

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



DII = Manufacturer's Marking
C3021LD = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 18 = 2018)
WW = Week (01 to 53)



Maximum Ratings N-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

Char	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	30	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Note 5)	I _D	8.5 7.1	А
Pulsed Drain Current (Note 6)	I _{DM}	26	Α

Maximum Ratings P-CHANNEL – Q1 (@ $T_A = +25$ °C, unless otherwise specified.)

Char	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	-30	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (Note 5)	I _D	-7.0 -4.5	А
Pulsed Drain Current (Note 6)	I _{DM}	-25	Α

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	2.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	50	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics N-CHANNEL – Q2 (@T_A = +25°C, unless otherwise specified.)

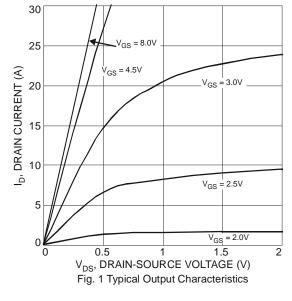
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1.0	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-Source Leakage	I_{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1	1.45	2.1	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
Static Drain-Source On-Resistance	D	_	14	21	mΩ	$V_{GS} = 10V, I_D = 7A$
Static Dialit-Source Off-Resistance	R _{DS(ON)}	_	18	32	11122	$V_{GS} = 4.5V, I_D = 5.6A$
Forward Transfer Admittance	Y _{fs}	_	8.1		S	$V_{DS} = 5V$, $I_D = 7A$
Diode Forward Voltage (Note 7)	V_{SD}	_	0.7	1.0	V	$V_{GS} = 0V$, $I_S = 1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	767	_	pF	10// 10
Output Capacitance	Coss	_	110	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	105	_	pF	1 = 1.0WH 12
Gate Resistance	R_g	_	1.4	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 4.5V)	Q_g	_	7.8	_	nC	
Total Gate Charge (V _{GS} = 10V)	Q_g	_	16.1	_	nC	Vps = 15V. lp = 9A
Gate-Source Charge	Q_{gs}	_	1.8	_	nC	VDS = 15V, ID = 9A
Gate-Drain Charge	Q_{gd}	_	2.5	_	nC	
Turn-On Delay Time	t _{D(ON)}	_	5.0	_	ns	
Turn-On Rise Time	t _R	_	4.5	_	ns	V _{GS} = 10V, V _{DS} = 15V,
Turn-Off Delay Time	t _{D(OFF)}	_	26.3	_	ns	$R_G = 6\Omega$, $I_D = 1A$
Turn-Off Fall Time	t _F	_	8.55	_	ns	

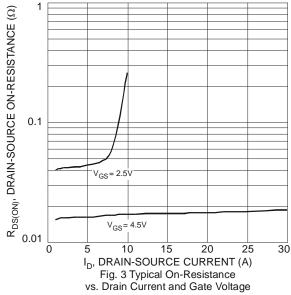
Notes:

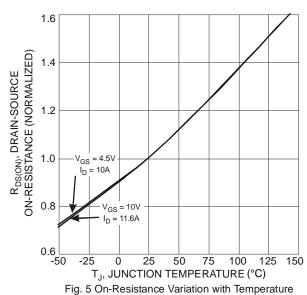
- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 6. Repetitive rating, pulse width limited by junction temperature.
- 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to production testing.

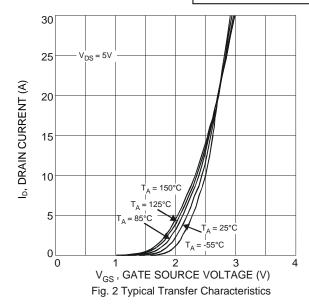












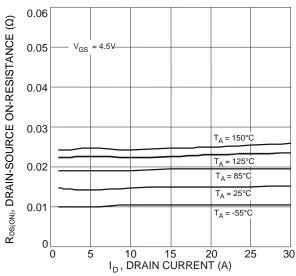


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

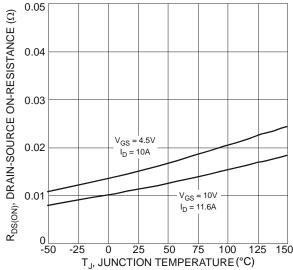


Fig. 6 On-Resistance Variation with Temperature

DMC3021LSD



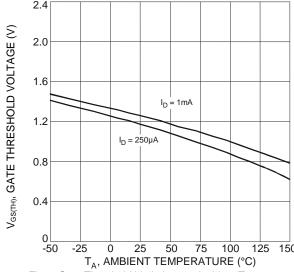
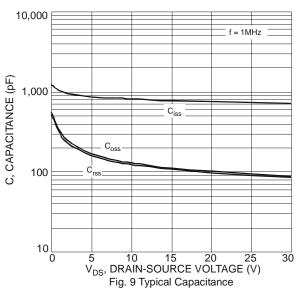
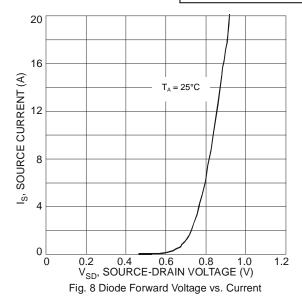


Fig. 7 Gate Threshold Variation vs. Ambient Temperature





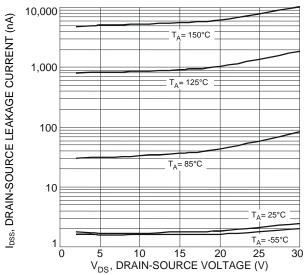


Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

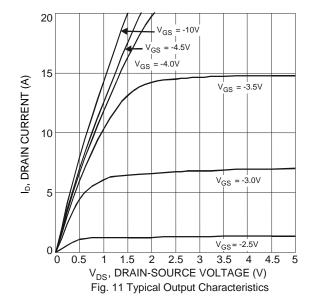


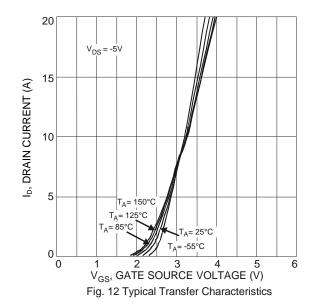
Electrical Characteristics P-CHANNEL - Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-30	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-1.0	μA	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-1	-1.7	-2.2	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance	Ь	_	30	39	mΩ	$V_{GS} = -10V, I_D = -4.3A$
Static Dialii-Source Off-Resistance	R _{DS(ON)}	_	42	53	11122	$V_{GS} = -4.5V, I_{D} = -3.7A$
Forward Transfer Admittance	Y _{fs}	_	7	_	S	$V_{DS} = -5V, I_{D} = -4.3A$
Diode Forward Voltage (Note 7)	V _{SD}	_	-0.75	-1.0	V	V _{GS} = 0V, I _S = -1.7A
DYNAMIC CHARACTERISTICS (Note 8)		•		•		
Input Capacitance	Ciss	_	1002		pF	101/11/
Output Capacitance	Coss	_	125		pF	$V_{DS} = -10V, V_{GS} = 0V,$ - f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	118		pF	I = 1.0WHZ
Gate Resistance	Rg	_	13	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = -4.5V)	Qg	_	10.1		nC	
Total Gate Charge (V _{GS} = -10V)	Qg	_	21.1		nC	15)/ 1 60
Gate-Source Charge	Q _{gs}	_	2.8	_	nC	$V_{DS} = -15V, I_{D} = -6A$
Gate-Drain Charge	Q_{gd}	_	3.2		nC	
Turn-On Delay Time	t _{D(ON)}	_	10.1	_	ns	
Turn-On Rise Time	t _R	_	6.5	_	ns	$V_{GS} = -10V, V_{DS} = -15V,$
Turn-Off Delay Time	t _{D(OFF)}	_	50.1	_	ns	$R_G = 6\Omega$, $I_D = -1A$
Turn-Off Fall Time	t _F	_	22.2	_	ns	<u>]</u>

Notes:

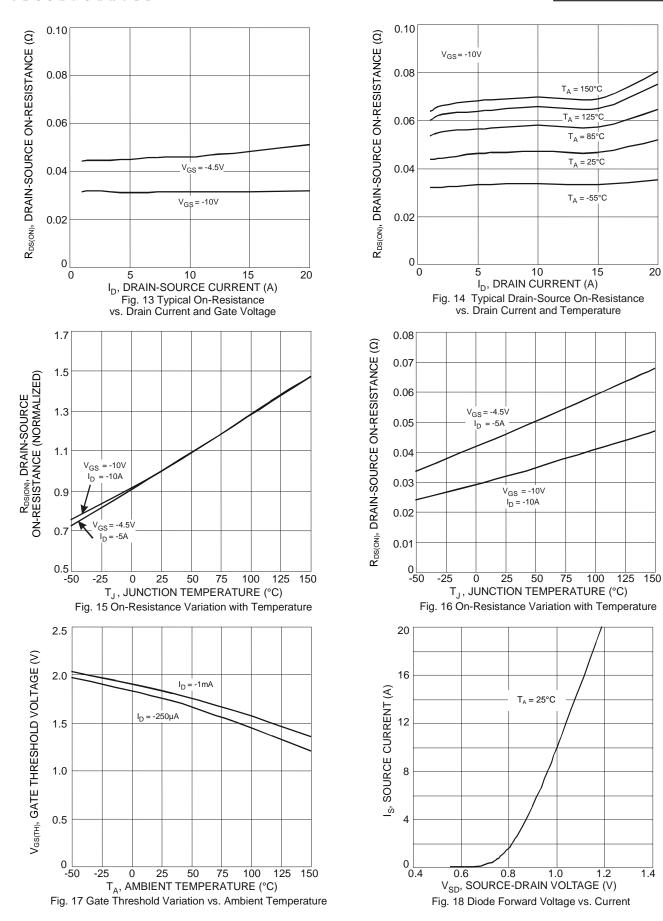
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to production testing.





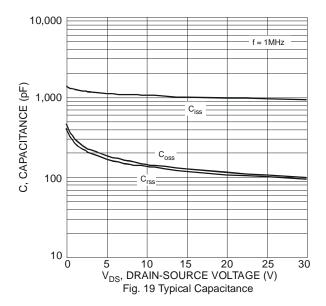
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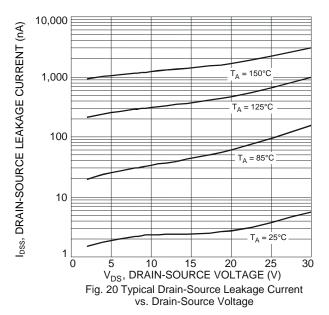




1.4





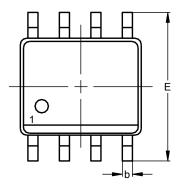


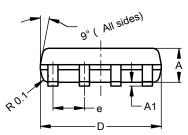


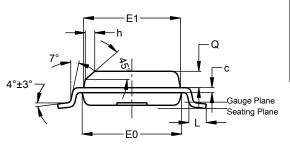
Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8





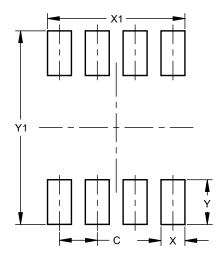


SO-8						
Dim	Min	Max	Тур			
Α	1.40	1.50	1.45			
A1	0.10	0.20	0.15			
b	0.30	0.50	0.40			
С	0.15	0.25	0.20			
D	4.85	4.95	4.90			
Е	5.90	6.10	6.00			
E1	3.80	3.90	3.85			
E0	3.85	3.95	3.90			
е			1.27			
h	-		0.35			
L	0.62	0.82	0.72			
Q	0.60	0.70	0.65			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



Dimensions	Value (in mm)
С	1.27
Х	0.802
X1	4.612
Y	1.505
Y1	6.50



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